



2009 INTERNATIONAL CONFERENCE ON COMPOUND SEMICONDUCTOR MANUFACTURING TECHNOLOGY

May 18th - 21st, 2009

Marriott – Waterside, Tampa, Florida, USA

CALL FOR PAPERS

Come to the 24th CS MANTECH in May 2009!

Our focus is optimum manufacturing practices for all compound semiconductor (CS) device technologies - the practical “nuts and bolts” of CS device production including design, materials, fabrication, and test.

We welcome submissions about all CS technologies. **Students are particularly encouraged to submit abstracts.** The program includes practical *Technical Sessions* including *Invited Papers* presented by technologists from around the world on a variety of topics, an intensive multi-topic *Workshop*, and an *Exhibit* featuring leading equipment, supply, substrate, epitaxy, and process chemical vendors and special service providers. *Events* like the *Exhibits Reception*, the *International Reception*, the *Interactive Forum*, and informal *Rump Sessions* provide opportunities to network and develop business contacts.

Manufacturing-Related Papers Solicited

Our mission is to foster the growth and success of the CS industry by encouraging the sharing of best manufacturing technologies and practices among peers in an open, informal environment. *Manufacturing technologies of interest include those for GaAs, InP, GaN and other nitrides, SiC, Diamond, Sb compounds, SiGe, and other related materials.* Papers addressing manufacturing challenges are sought in, but not limited to, the following subject areas:

MANUFACTURING

- Fab Optimization
- Foundry Operations
- Technology Transfers
- Cycle-Time Reduction
- Production Modeling
- Design Strategies
- Quality and Training
- Tool Selection
- Environmental Impact
- Yield & SPC

PROCESSING/ CONTROL

- Lithography
- Etch & Etch Stops
- Gate Formation
- Metrology
- Novel Control Techniques
- Backend and Backside
- Thin Films & Metallization
- Multi-Level Interconnects

RF DEVICE TECHNOLOGIES:

- MESFET, HFET, HEMT
- PHEMT, MHEMT
- HBT, PIN, MEMS
- Performance & Yield
- Process Simplification
- Heterogeneous Integration
- Device Tech Integration
- Integrated Passives

TEST & RELIABILITY

- High Volume/ Low Cost
- In-Process
- Test Structures
- On-Chip Self Test
- Failure Modes/ Analysis
- Fault Identification
- Reliability Testing
- ESD

OPTICAL DEVICES & CIRCUITS

- LEDs, VCSELS
- Lasers, OEICs
- Modulators & Detectors
- Waveguides
- Lighting Technologies
- Process Simplification
- Fabrication Control
- Process & Circuit Integration

EMERGING AND COMPETING TECHNOLOGIES

- Wide Bandgap
- Narrow Bandgap
- InP, SiGe, Strained Si
- Plasma Wave Devices
- Si CMOS, LDMOS
- New Technologies

MATERIALS

- Availability & Quality
- Standards
- Cost Reduction
- Recycling
- Epitaxy
- Metamorphic Material

PACKAGING

- High Frequency
- Bump and Flip Chip
- System in Package
- Hermeticity & Reliability
- Thermal Management
- Photonic Packaging
- 3-D Packaging & Pb-Free MSL

FUTURE

- Technology Roadmap
- Business Outlook
- “Killer” Applications
- New Paradigms

SPECIAL SESSION:

COMPOUND SOLAR TECHNOLOGY

- CS Solar Cells
- Solar Manufacturing
- Concentrator vs. Flat Panel
- Business Models

ABSTRACTS DUE OCTOBER 31, 2008

Send a 1- or 2-page abstract in PDF or WORD format to abstracts@csmantech.org

Please use U.S. fonts only.

Look for abstract guidelines at www.csmantech.com

Conference Chair
Scott Davis
sdavis@sesmi.com

Technical Program Chair
Steve Mahon
smahon@tqs.com

Registration Chair
Russ Kremer
russ@fcm-us.com

Exhibits Chair
Mike Barsky
mike.barsky@ngc.com

Publicity Chair
Miriam Sadaka
mariam.sadaka@gmail.com

University Liaison
Drew Hanser
hanser@kymatech.com

Abstracts should clearly state:

- The **Purpose** of the work.
- How CS **Manufacturing Technology** was advanced or how a competing technology relates to CS devices.
- What **Specific Results** were obtained? Supporting data, charts and pictures are requested.

All abstracts should include keywords to facilitate indexing for classification and search in our database. Papers describing related work performed in university or government centers should clearly describe the application to manufacturing. **Student Papers** should be clearly identified as such. An annual prize is given for the best student paper presented at the conference.

Note: Large files over 1 MB in size may not transmit successfully. Please use self-extracting or “zip” files to facilitate transmission of such large files.

Notice of paper acceptance will be e-mailed no later than **December 15, 2008**. Authors of accepted papers must submit a publication-ready extended abstract by **February 9, 2009**. The extended abstracts will be published in the MANTECH Conference Digest and will become the property of GaAs MANTECH, Inc. It is the author’s responsibility to obtain any required clearance prior to submission of both the abstract and the extended abstract.

Students and University researchers seeking financial assistance to attend the Conference should contact Scott Davis at student.aid@csmantech.org.



Downtown Tampa Skyline

Exhibitors: Please watch for updates of exhibitors’ information at the conference website www.csmantech.org.

Conference Sponsorship: Please e-mail Sponsorships@csmantech.org to receive information on conference sponsorship opportunities.

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Tampa, Florida

This is a city with everything to shake away the winter blahs. From white sand beaches to a cosmopolitan downtown to world class attractions, Tampa is the place. The Tampa Marriott Waterside is in downtown Tampa, steps from the marina and walking distance to many great restaurants and attractions. So if you want a hand-rolled cigar in Yorba City, a cruise in the bay, or a visit to the world class aquarium, Tampa is for you

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